Notes:
1. Q904, Q905, R927, R928, R929, R930, T901 are reworked parts.
2. Rework needed for the connection of U901 pin 8 to Vin node on PMP10974RevA PCB.

85VAC to 265VAC Input

Heat sink required

Heat sink required

Np:nex:nsec=16:4:1

PMP11232

10/18/2015

Sheng-Yang Yu

Drawn By: Sheng-Yang Yu

Heat sink required

Engineer:

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